

TUN-568US

PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Applicant: Rongjia Tao et al.

Serial No.: 10/007,575

Filed: November 9, 2001

FOR: METHOD AND APPARATUS FOR
INCREASING AND MODULATING
THE YIELD SHEAR STRESS OF
ELECTORHEOLOGICAL FLUIDS

: Art Unit:

: Examiner:

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INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents

Washington, D.C. 20231

SIR:

Pursuant to 37 C.F.R. §§ 1.97 and 1.98 and to the duty of disclosure set forth in 37 C.F.R. § 1.56, the Examiner in charge of the above-identified application is requested to consider and make of record the references listed on the PTO 1449 (R&P) submitted herewith. A copy of each of the listed references is also enclosed.

Although the information submitted herewith may be "material" to the Examiner's consideration of the subject application, this submission is not intended to constitute an admission that such information is "prior art" as to the claimed invention.

In accordance with 37 C.F.R. § 1.97(g), the filing of this Information Disclosure Statement shall not be construed to mean that a search has been made.

This information disclosure statement is being filed within three months of the filing date of the above-referenced application. No first Official Action has yet been received and it is presumed that none has yet been mailed. No Fee or certification is required. 37 C.F.R. § 1.97(b).

Respectfully submitted,



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Attorneys for Applicants

HSN/mc

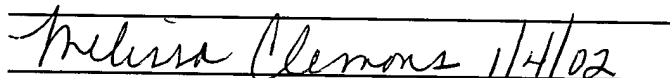
Encls.: PTO Form 1449,
Copy of (16) References

Dated: January 4, 2002

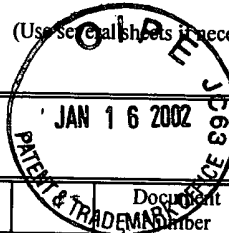
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The Assistant Commissioner for Patents is hereby authorized to charge payment to Deposit Account No. 18-0350 of any fees associated with this communication.

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on:



FORM PTO-1449 (Rev. 2-32) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Information Disclosure Statement by Applicant (Use several sheets if necessary)	ATTY. DOCKET NO. TUN-568US	SERIAL NO 10/007,575
	APPLICANT Rongjia Tao et al.	
	FILING DATE November 9, 2001	GROUP



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U.S. PATENT DOCUMENTS

Exmr Initial	Document Number	Date	Name	Class	Sub Class	Filing Date
	Re. 35,773	04/21/1998	Okada et al.			
	Re. 37,015E	01/16/2001	Rensel et al.			
	5,507,967	04/16/1996	Fujita et al.			
	5,558,803	09/24/1996	Okada et al.			
	5,843,331	12/01/1998	Schober et al.			
	5,891,356	04/06/1999	Inoue et al.			
	6,027,429	02/22/2000	Daniels			
	6,096,235	08/01/2000	Asako et al.			
	6,116,257	09/12/2000	Yokota et al.			
	6,149,166	11/21/2000	Struss et al.			
	6,159,396	12/12/2000	Fujita et al.			

FOREIGN PATENT DOCUMENTS

Exmr Initial	Document Number	Date	Country	Class	Sub Class	Translation YES NO

OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

	1)	R. Tao et al., "Three-Dimensional Structure of Induced Electrorheological Solid", Phys. Rev. Lett., Vol. 67, No. 3, 15 July 1991, pps. 398-401
	2)	Chen et al., "Laser Diffraction Determination of the Crystalline Structure of an Electrorheological Fluid", Phys. Rev. Lett., Vol. 68, No. 16, 20 April 1992, pps. 2555-2558
	3)	G.L. Gulley et al., "Static Shear Stress of Electrorheological Fluids", Phys. Rev. E, Vol. 48, No. 4 October 1993, pps. 2744-2751
	4)	X. Tang et al., "Structure-enhanced Yield Stress of Magnetorheological Fluids", J. of Applied Physics, Vol. 87, No. 5, 1 March 2000, pps. 2634-2638
	5)	R. Tao et al., "Electrorheological Fluids Under Shear", International J. of Modern Physics B, Vol. 15, 2001

Examiner	Date Considered
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Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.